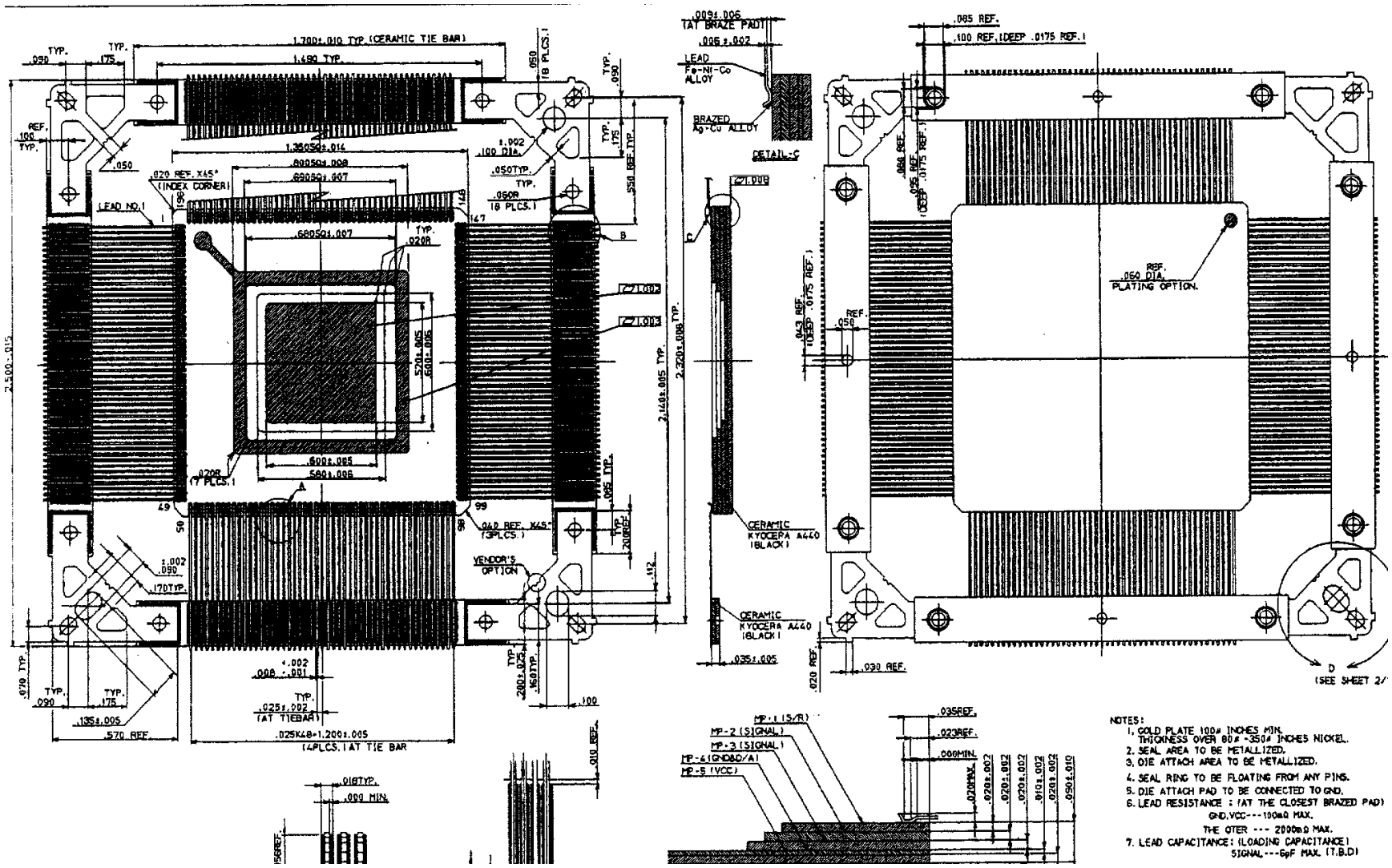

NOTES:

1. GOLD PLATE 100# INCHES MIN. THICKNESS OVER 80# -350# INCHES NICKEL.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING TO BE FLOATING FROM ANY PINS.
5. DIE ATTACH PAD TO BE CONNECTED TO GND.
6. LEAD RESISTANCE : (AT THE CLOSEST BRAZED PAD)
   GND,VCC---100mΩ MAX.
   THE OTER --- 2000mΩ MAX.
7. LEAD CAPACITANCE: (LOADING CAPACITANCE)
   SIGNAL---6pF MAX. (T.B.D)